

HEXFRED® Ultrafast Diodes, 300 A (INT-A-PAK Power Modules)


INT-A-PAK
FEATURES

- Electrically isolated: DCB base plate
- Standard JEDEC® package
- Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- Case style INT-A-PAK
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


**RoHS
COMPLIANT**
PRIMARY CHARACTERISTICS

V_R	1200 V
V_F (typical) at 300 A at 25 °C	2.18 V
t_{rr} (typical) at 45 A	233 ns
$I_{F(DC)}$ at T_C	300 A at 60 °C
Package	INT-A-PAK
Circuit configuration	Single diode

REMARKS

- Product reliability results valid for $T_J = 150$ °C
- Recommended operation temperature $T_{op} = 150$ °C

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Continuous forward current	I_F	$T_C = 25$ °C	375	A
		$T_C = 60$ °C	300	
Single pulse forward current	I_{FSM}	$T_J = 25$ °C	2400	
Maximum power dissipation	P_D	$T_C = 25$ °C	1040	W
		$T_C = 60$ °C	750	
RMS isolation voltage	V_{ISOL}	50 Hz, circuit to base, all terminal shorted, $t = 1$ s	3500	V
Junction temperature range	T_J		-40 to +150	°C
Storage temperature range	T_{Stg}		-40 to +150	

ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 500$ μ A	1200	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 300$ A	-	2.18	2.23	
		$I_F = 300$ A, $T_J = 150$ °C	-	2.24	2.47	
Maximum reverse leakage current	I_{RM}	$V_R = 1200$ V	-	0.06	0.2	mA
		$T_J = 150$ °C, $V_R = 1200$ V	-	-	20	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode reverse recovery charge	Q _{rr}	T _J = 25 °C	I _F = 45 A V _R = 400 V di _F /dt = 500 A/μs	-	3.5	-	μC
		T _J = 125 °C		-	10.4	-	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	233	-	ns
		T _J = 125 °C		-	396	-	
Reverse recovery current	I _{rr}	T _J = 25 °C		-	30	-	A
		T _J = 125 °C		-	53	-	

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum internal thermal resistance, junction to case per leg	R _{thJC}	DC operation	0.12	°C/W
Typical thermal resistance, case to heatsink per module	R _{thCS}	Mounting surface flat, smooth, and greased	0.05	
Mounting torque ± 10 %		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound	4 to 6	Nm
to heatsink				
Approximate weight			200	g
			7.1	oz.
Case style			INT-A-PAK	

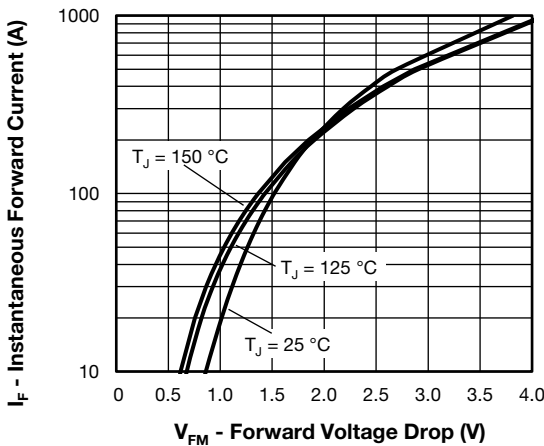


Fig. 1 - Typical Forward Voltage Drop Characteristics

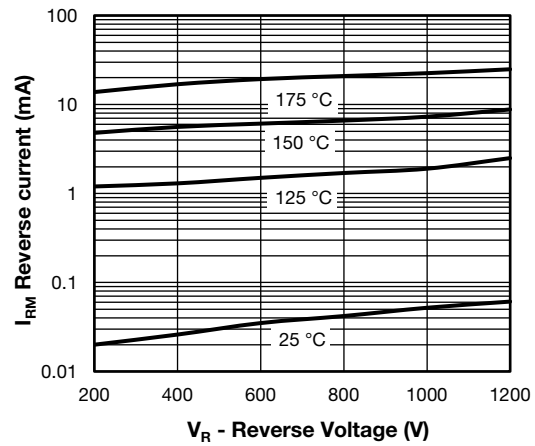


Fig. 2 - Typical Value of Reverse Current vs. Reverse Voltage

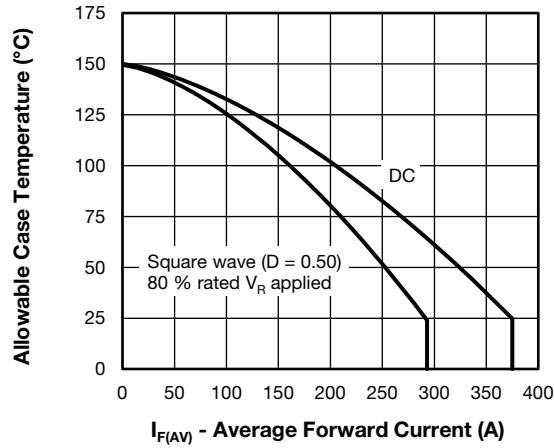


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

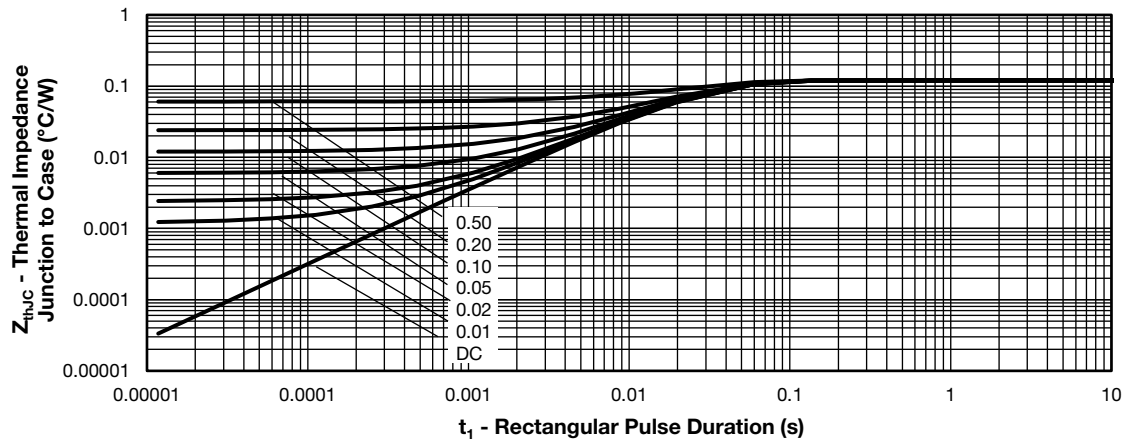


Fig. 4 - Maximum Thermal Impedance R_{thJC} Characteristics

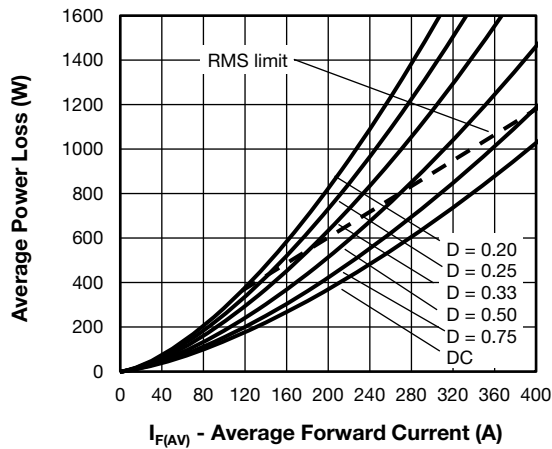


Fig. 5 - Forward Power Loss Characteristics

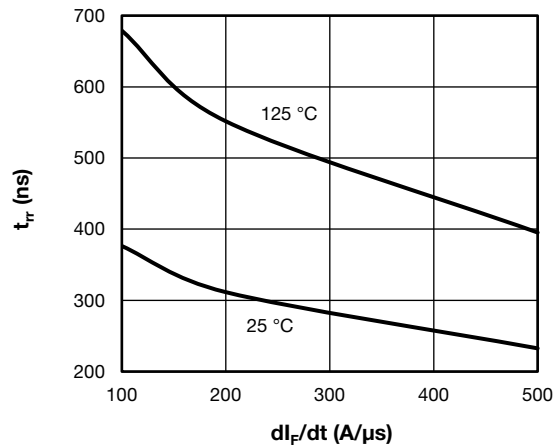


Fig. 6 - Typical Reverse Recovery Time vs. di_F/dt

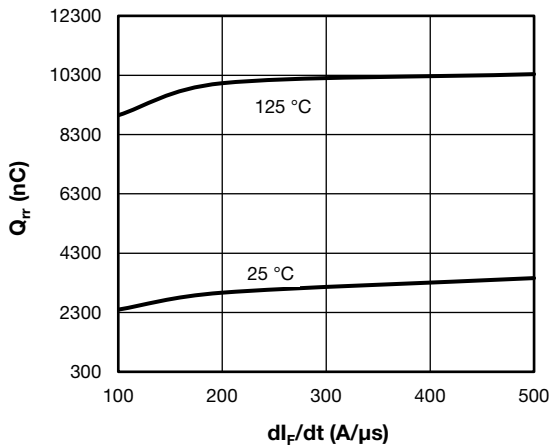


Fig. 7 - Typical Reverse Recovery Charge vs. di_F/dt

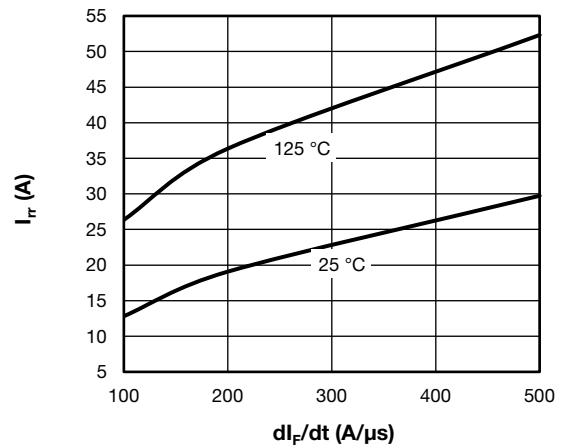


Fig. 8 - Typical Reverse Recovery Current vs. di_F/dt

ORDERING INFORMATION TABLE

Device code	VS-VS	KE	U	300	/	12	PbF
	①	②	③	④		⑤	⑥

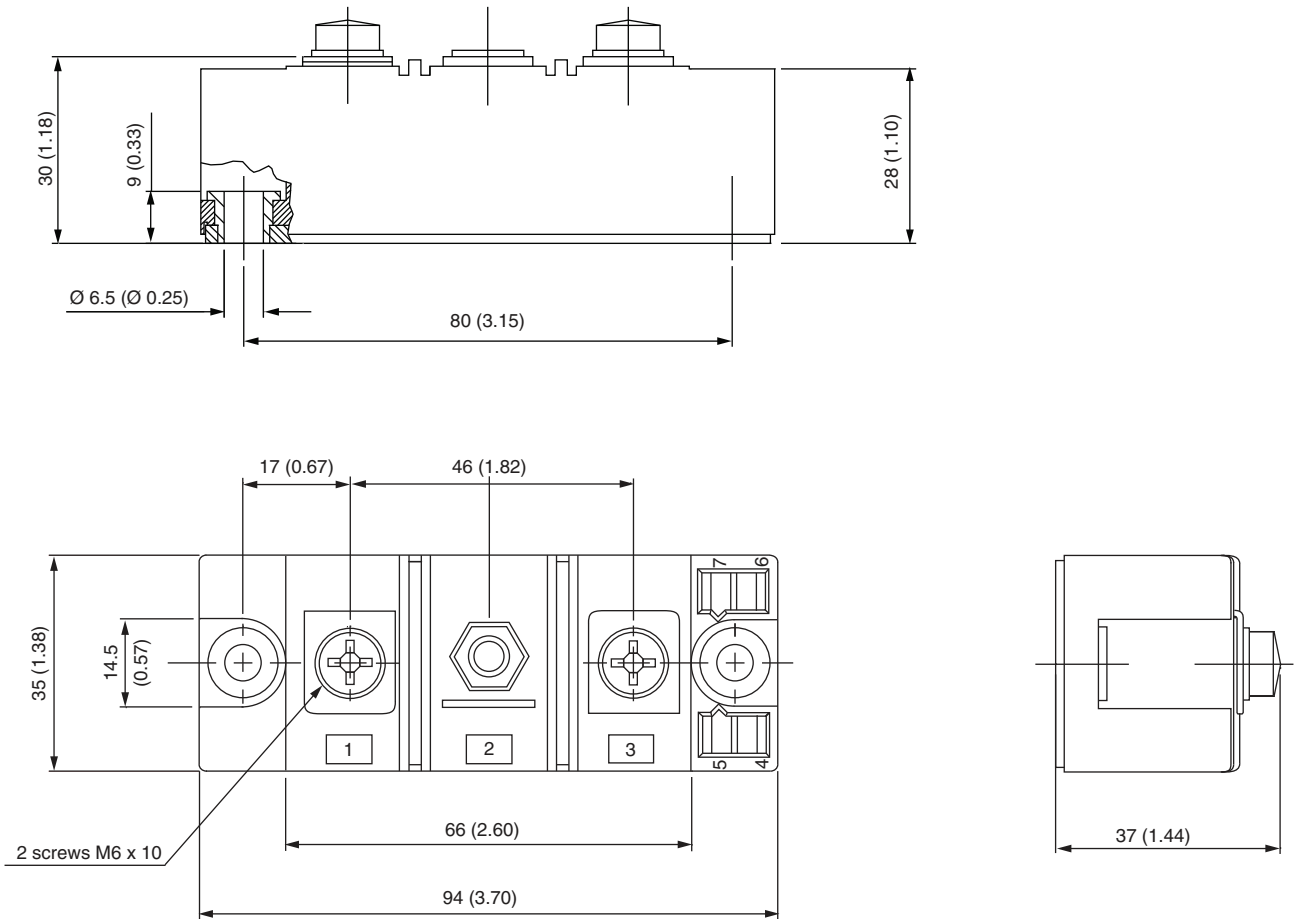
- 1** - Vishay Semiconductors product
- 2** - KE = circuit configuration
- 3** - U = ultrafast diode
- 4** - Current rating 300 = 300 A
- 5** - Voltage rating (12 = 1200 V)
- 6** - PbF = lead (Pb)-free

CIRCUIT CONFIGURATION





DIMENSIONS in (inches) millimeters **INT-A-PAK DBC**



INT-A-PAK DBC

DIMENSIONS in millimeters (inches)





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